## International IER Rectifier

- Advanced Process Technology
- Ultra Low On-Resistance
- Dynamic dv/dt Rating
- $175^{\circ} \mathrm{C}$ Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- $100 \% \mathrm{R}_{\mathrm{G}}$ Tested
- Lead-Free


## Description

Advanced HEXFET ${ }^{\circledR}$ Power MOSFETs from International Rectifier utilize advanced processing techniques to achieve extremely low onresistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The $D^{2}$ Pak is a surface mount power package capable of accommodating die sizes up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D²Pak is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0W in a typical surface mount application. The through-hole version (IRL2203NL) is available for low-profile applications.


## Absolute Maximum Ratings

| Symbol | Parameter | Max | Units |
| :---: | :---: | :---: | :---: |
| $\mathrm{l}_{\mathrm{D}} @ \mathrm{~T}_{\mathrm{C}}=25^{\circ} \mathrm{C}$ | Continuous Drain Current, VGS @ 10V | 116 \% | A |
| $\mathrm{l}_{\mathrm{D}}$ @ $\mathrm{T}_{\mathrm{C}}=100^{\circ} \mathrm{C}$ | Continuous Drain Current, VGS @ 10V | 82 |  |
| IDM | Pulsed Drain Current (1) | 400 |  |
| $\mathrm{P}_{\mathrm{D}} @ \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ | Power Dissipation | 3.8 | W |
| $\mathrm{P}_{\mathrm{D}} @ \mathrm{~T}_{\mathrm{C}}=25^{\circ} \mathrm{C}$ | Power Dissipation | 180 | W |
|  | Linear Derating Factor | 1.2 | W/ ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{V}_{\mathrm{GS}}$ | Gate-to-Source Voltage | $\pm 16$ | V |
| $\mathrm{t}_{\text {AR }}$ | Avalanche Current (1) | 60 | A |
| $\mathrm{E}_{\text {AR }}$ | Repetitive Avalanche Energy (1) | 18 | mJ |
| dv/dt | Peak Diode Recovery dv/dt (3) | 5.0 | $\mathrm{V} / \mathrm{ns}$ |
| $\mathrm{T}_{J}$ | Operating Junction and Storage Temperature Range | -55 to +175 | ${ }^{\circ} \mathrm{C}$ |
| T STG | Soldering Temperature, for 10 seconds | 300 (1.6mm from case) |  |

## Thermal Resistance

| Symbol | Parameter | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: |
| $\mathrm{R}_{\text {өJC }}$ | Junction-to-Case ${ }^{(9)}$ | - | 0.85 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| $\mathrm{R}_{\text {өJA }}$ | Junction-to-Ambient (PCB mount, steady state) (8) ${ }^{(6)}$ | - | 40 |  |

IRL2203NS/LPbF
Electrical Characteristics @ $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}$ (unless otherwise specified)
Internationa IgR Rectifier


Source-Drain Ratings and Characteristics

| Symbol | Parameter | Min | Typ | Max | Units | Conditions |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Is | Continuous Source Current (Body Diode) | - | - | 116 (2) | A | MOSFET symbol showing the |
| ISM | Pulsed Source Current <br> (Body Diode) <br> (1) | - | - | 400 |  | integral reverse <br> p -n junction diode. |
| $\mathrm{V}_{\text {SD }}$ | Diode Forward Voltage | - | - | 1.2 | V | $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}, \mathrm{I}_{\mathrm{S}}=60 \mathrm{~A}, \mathrm{~V}_{\mathrm{GS}}=0 \mathrm{~V} \oplus$ |
| $\mathrm{t}_{\text {rr }}$ | Reverse Recovery Time | - | 56 | 84 | ns | $\begin{aligned} & T_{J}=25^{\circ} \mathrm{C}, \mathrm{I}_{\mathrm{F}}=60 \mathrm{~A} \\ & \mathrm{di} / \mathrm{dt}=100 \mathrm{~A} / \mu \mathrm{s} \oplus \end{aligned}$ |
| $\mathrm{Q}_{\mathrm{rr}}$ | Reverse Recovery Charge | - | 110 | 170 | nC |  |
| ton | Forward Turn-On Time | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD) |  |  |  |  |

## Notes:

(1) Repetitive rating; pulse width limited by max. junction temperature. ( See fig. 11)
(2) Starting $\mathrm{T}_{\mathrm{J}}=25^{\circ} \mathrm{C}, \mathrm{L}=0.16 \mathrm{mH} \mathrm{R}_{\mathrm{G}}=25 \Omega$, $I_{\mathrm{AS}}=60 \mathrm{~A}, \mathrm{~V}_{\mathrm{GS}}=10 \mathrm{~V}$ (See Figure 12)
(3) $\mathrm{I}_{\mathrm{SD}} \leq 60 \mathrm{~A}, \mathrm{di} / \mathrm{dt} \leq 110 \mathrm{~A} / \mu \mathrm{s}, \mathrm{V}_{\mathrm{DD}} \leq \mathrm{V}_{(\mathrm{BR}) \mathrm{DSS}}$, $\mathrm{T}_{\mathrm{J}} \leq 175^{\circ} \mathrm{C}$
(4) Pulse width $\leq 400 \mu$ s; duty cycle $\leq 2 \%$.
(5) This is a typical value at device destruction and represents operation outside rated limits.
(6) This is a calculated value limited to $\mathrm{T}_{J}=175^{\circ} \mathrm{C}$.
(7) Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 75A.
(8) When mounted on 1 " square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note \#AN-994.
(9) $\mathrm{R}_{\theta}$ is measured at $T_{J}$ approximately $90^{\circ} \mathrm{C}$

## IRL2203NS/LPbF

$D^{2}$ Pak Package Outline
Dimensions are shown in millimeters (inches)


| $\begin{aligned} & \hline S \\ & Y \\ & M \\ & M \\ & B \\ & O \\ & L \end{aligned}$ | DIMENSIONS |  |  |  | $N$$N$$O$$T$$E$$S$ |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  | MILLIMETERS |  | inches |  |  |
|  | MIN. | MAX. | MIN. | MAX. |  |
| A | 4.06 | 4.83 | . 160 | . 190 |  |
| A1 |  | 0.127 |  | . 005 |  |
| b | 0.51 | 0.99 | . 020 | . 039 |  |
| b1 | 0.51 | 0.89 | . 020 | . 035 | 4 |
| b2 | 1.14 | 1.40 | . 045 | . 055 |  |
| c | 0.43 | 0.63 | . 017 | . 025 |  |
| c1 | 0.38 | 0.74 | 015 | 029 | 4 |
| c2 | 1.14 | 1.40 | . 045 | . 055 |  |
| D | 8.51 | 9.65 | . 335 | . 380 | 3 |
| D1 | 5.33 |  | 210 |  |  |
| E | 9.65 | 10.67 | . 380 | . 420 | 3 |
| E1 | 6.22 |  | . 245 |  |  |
| e | 2.54 BSC |  | . 100 BSC |  |  |
| L | 14.61 | 15.88 | . 575 | . 625 |  |
| L1 | 1.78 | 2.79 | . 070 | . 110 |  |
| L2 |  | 1.65 |  | . 065 |  |
| L3 | 1.27 | 1.78 | . 050 | . 070 |  |
| L4 | 0.25 BSC |  | . 010 BSC |  |  |
| m | 17.78 |  | . 700 |  |  |
| m1 | 8.89 |  | . 350 |  |  |
| n | 11.43 |  | . 450 |  |  |
| $\bigcirc$ | 2.08 |  | . 082 |  |  |
| $p$ | 3.81 |  | . 150 |  |  |
| $\theta$ | $90^{\circ}$ | $93^{\circ}$ | $90^{\circ}$ | $93^{\circ}$ |  |



1. Dimensioning and tolerancing per asme y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. DIMENSION D \& E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"]
4. Dimension b1 and c1 Apply to base metal only.
5. CONTROLLING DIMENSION: INCH.

## D2Pak Part Marking Information (Lead-Free)

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EXAMPLE: \(\begin{aligned} & \text { THIS IS AN IRF } 530 \text { S WITH } \\ & \\ & \text { LOT CODE } 8024\end{aligned}\) OT CODE 8024 ASSEMBLED ON WW 02, 2000 IN THE ASSEMBLY LINE "L"
Note: "P" in as sembly line pos ition indicates "Lead-F ree"
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OR


## IRL2203NS/LPbF

## D²Pak Tape \& Reel Information

Dimensions are shown in millimeters (inches)


## NOTES

1. COMFORMS TO EIA-418.
2. CONTROLLING DIMENSION: MILLIMETER.


Data and specifications subject to change without notice. This product has been designed and qualified for the Automotive [Q101] market.

$$
\begin{aligned}
& \text { International } \\
& \text { I@R Rectifier }
\end{aligned}
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